



PATENT
Atty. Docket: 10191/1466

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Volker BECKER, *et al.*

Serial No. : 09/581,663

Filed : August 3, 2000

For : METHOD FOR PROCESSING SILICON
BY ETCHING PROCESSES

Group Art Unit : 1746

Examiner : S. AHMED

MAILED

APR 15 2002

GROUP 1700

COPY OF PAPER
ORIGINALLY FILED

Assistant Commissioner
for Patents
Washington D.C. 20231

I hereby certify that this correspondence is being deposited
with the United States Postal Service as first class mail in an
envelope addressed to: Assistant Commissioner for Patents,
Washington, D.C. 20231 on

Date: 3/27, 2002

Reg. No. 36,197

Signature: _____

Jong H. Lee

AMENDMENT

Sir:

In response to the Office Action mailed December 21, 2001, the Applicants respectfully submit the following amendments and remarks. The Applicants respectfully request a one-month Extension of Time to respond to the Office Action. The extended period expires on April 22, 2002, due to the one-month extended due date falling on a Sunday.

04/22/2002 ASINLET 00000005 110600 03581663

01 FC:102

500.00 CH

02 FC:103

125.00 CH

Please cancel claims 1-31, without prejudice to the subject matter therein.

Please add the following new claims 32-69:

32. (New) A method for etching a silicon layered body, which has a first silicon layer (15) that is provided with an etching mask (10) for defining lateral recesses (21);